ABSTRACT OF THE DISCLOSURE

A method and a measuring instrument for determining the position of an edge to be measured on a pattern on a substrate are described. A complete, nonlinear model intensity profile, which identifies the edge to be measured, of a model edge is ascertained and stored, and a desired edge position \mathbf{x}_k is defined therein with subpixel accuracy. A camera image of the substrate having the edge to be measured is acquired, and a one-dimensional measured intensity profile of the edge to be measured is determined therefrom. The model intensity profile is identified in the measured intensity profile with an indication of its location \mathbf{x}_m relative to a reference point. The desired position \mathbf{p} of the edge to be measured is determined with subpixel accuracy as $\mathbf{p} = \mathbf{x}_m + \mathbf{x}_k$.

(FIG. 8)